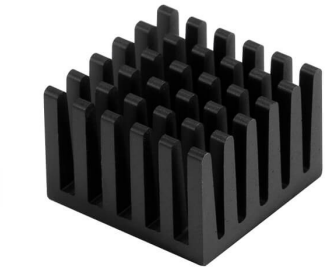
CUI DEVICES

MODEL: HSB05-171711 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- aluminum alloy
- black anodized finish



RoHS

MODEL

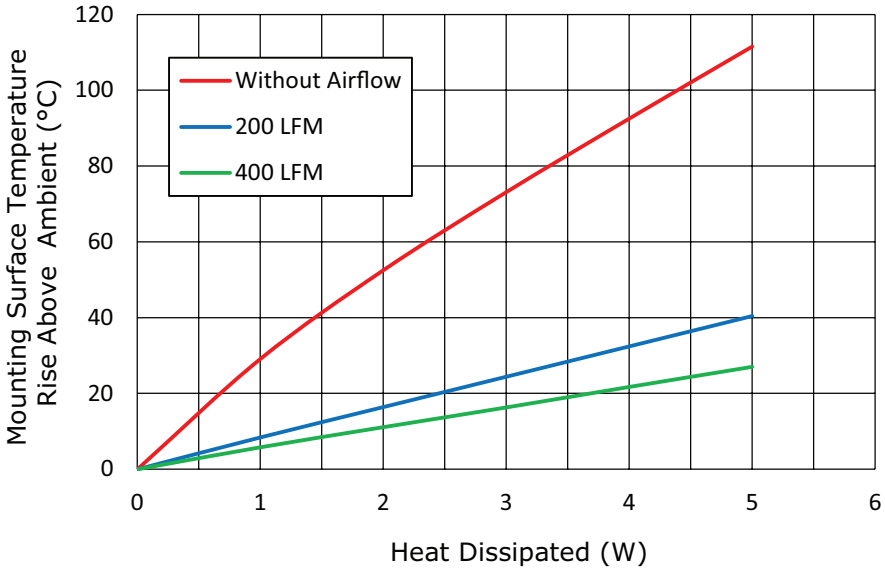
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSB05-171711	23.91	29.1	8.4	5.8	3.14

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	29.1	8.4	5.8
2	52.5	16.4	11.1
3	73.1	24.4	16.3
4	92.5	32.4	21.7
5	111.5	40.2	27.0

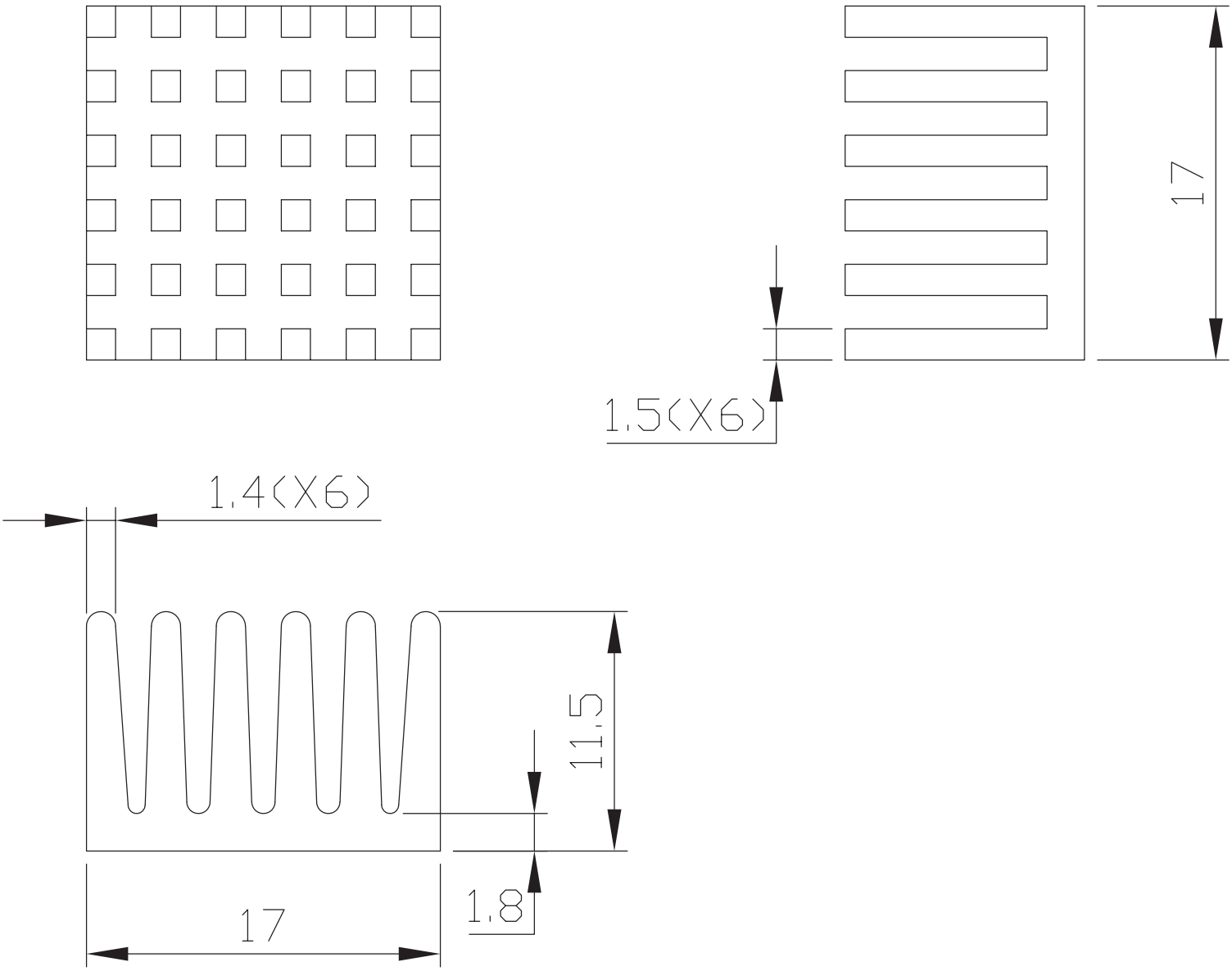
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	3.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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